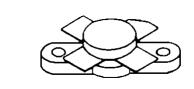


## **SD1446**

# RF & MICROWAVE TRANSISTORS HF/VHF APPLICATIONS

- 50 MHz
- 12.5 VOLTS
- EFFICIENCY 55%
- **COMMON EMITTER**
- GOLD METALLIZATION
- P<sub>OUT</sub> = 70 W MIN. WITH 10 dB GAIN

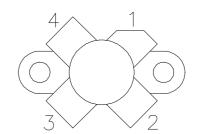


.380 4LFL (M113)

epoxy sealed

ORDER CODE SD1446 BRANDING SD1446

#### **PIN CONNECTION**



- 1. Collector
- 3. Base
- 2. Emitter
- 4. Emitter

## **DESCRIPTION**

The SD1446 is a 12.5 V Class C epitaxial silicon NPN planar transistor designed primarily for land mobile transmitter applications. This device utilizes emitter ballasting and is extremely stable and capable of withstanding high VSWR under operating conditions.

## **ABSOLUTE MAXIMUM RATINGS** $(T_{case} = 25^{\circ}C)$

Symbol	Parameter	Value	Unit	
$V_{CBO}$	Collector-Base Voltage	36	V	
V <sub>CEO</sub> Collector-Emitter Voltage		18	V	
V <sub>EBO</sub>	V <sub>EBO</sub> Emitter-Base Voltage 3.8		V	
Ic	Device Current	12.0	Α	
Poiss	Power Dissipation	183	W	
TJ	Junction Temperature	+200	°C	
T <sub>STG</sub>	Storage Temperature	- 65 to +150	°C	

#### THERMAL DATA

	· <del>-</del> · <del>-</del>		
R <sub>TH(j-c)</sub>	Junction-Case Thermal Resistance	1.05	°C/W

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## **ELECTRICAL SPECIFICATIONS** (T<sub>case</sub> = 25°C)

## **STATIC**

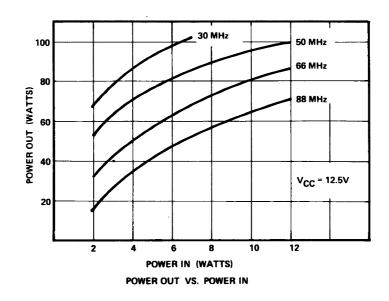
Symbol	Test Conditions		Value			Unit	
		М	lin.	Тур.	Max.	Oiiit	
BV <sub>CBO</sub>	$I_C = 50mA$	$I_E = 0mA$	3	36	_	_	V
BV <sub>CES</sub>	I <sub>C</sub> = 100mA	$V_{BE} = 0V$	3	36		_	V
BV <sub>CEO</sub>	$I_C = 50mA$	$I_B = 0mA$	1	18		_	V
BV <sub>EBO</sub>	I <sub>E</sub> = 10mA	$I_C = 0mA$	3	3.5		_	V
Ices	V <sub>CE</sub> = 15V	I <sub>E</sub> = 0mA	_	_	_	10	mA
hFE	V <sub>CE</sub> = 5V	$I_C = 5A$	1	10		_	_

#### **DYNAMIC**

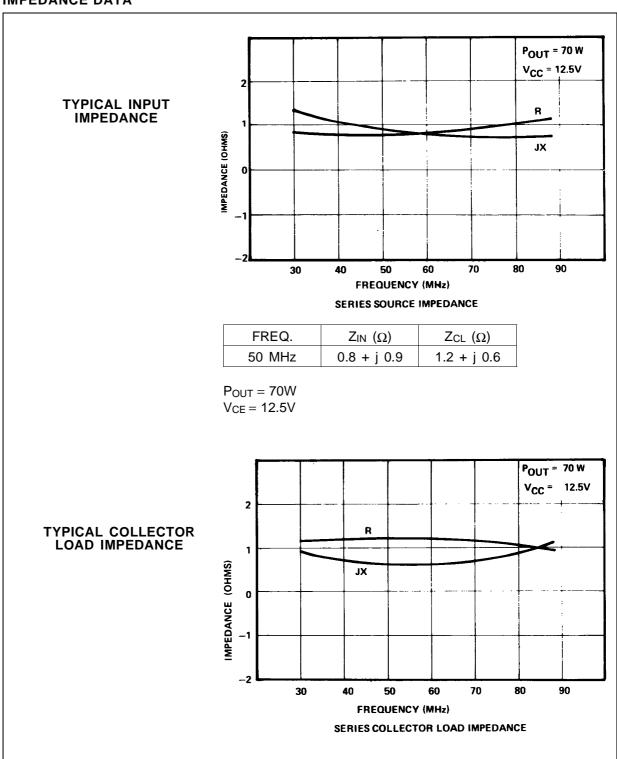
Symbol	Test Conditions			Value			Unit
Symbol				Min.	Тур.	Max.	Unit
Pout	f = 50 MHz	$P_{IN} = 7 W$	$V_{CE} = 12.5 \text{ V}$	70	_	_	W
G <sub>P</sub>	f = 50 MHz	$P_{IN} = 7 W$	$V_{CE} = 12.5 \text{ V}$	10	_	_	dB
η <sub>C</sub>	f = 50 MHz	$P_{IN} = 7 W$	$V_{CE} = 12.5 V$	_	55	_	%
Сов	f = 1 MHz	V <sub>CB</sub> = 12.5V		_	_	300	pF

## **TYPICAL PERFORMANCE**

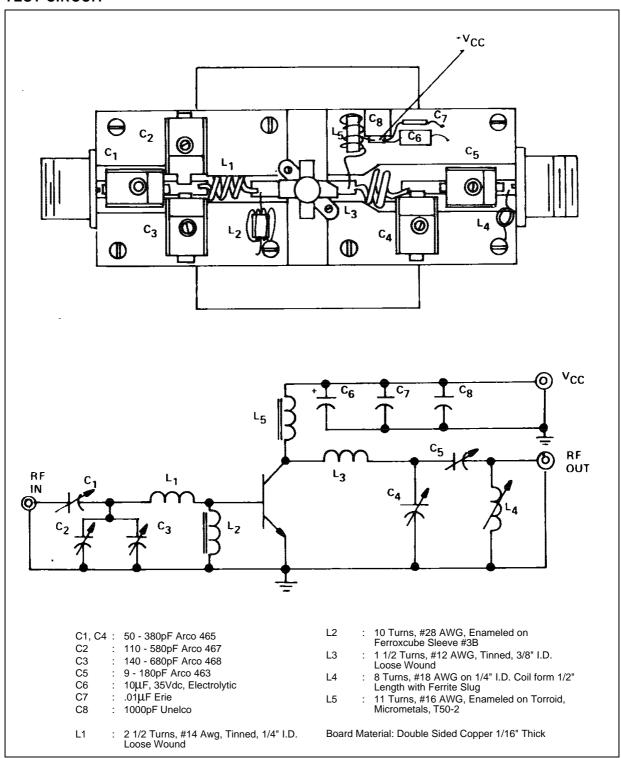
## **POWER OUTPUT vs POWER INPUT**



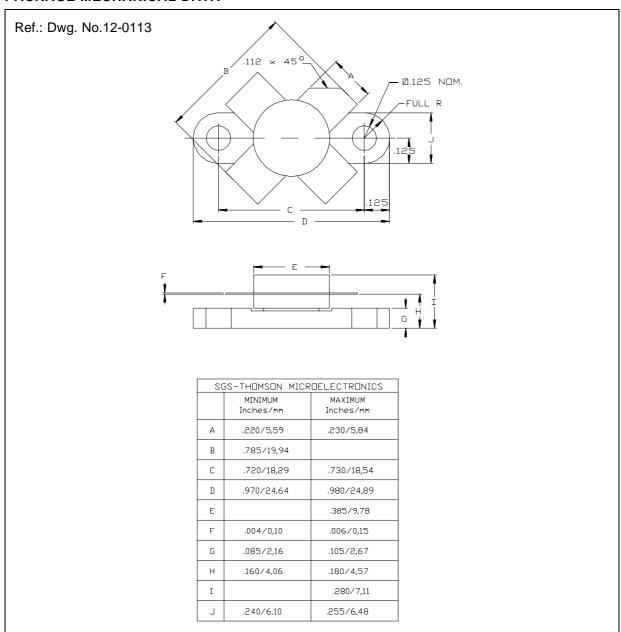
#### **IMPEDANCE DATA**



#### **TEST CIRCUIT**



#### **PACKAGE MECHANICAL DATA**



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